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Invensas Signs BVA Technology License and Development Agreement with ASE

Invensas BVA® Technology Enables Low Cost, Low Profile, Scalable Package-on-Package Solution for Future Generations of Application Processors and SiP Solutions

SAN JOSE, Calif.--(BUSINESS WIRE)-- Tessera Technologies, Inc. (Nasdaq:TSRA), announced today that its wholly owned subsidiary Invensas Corporation signed a new technology license and development agreement with Advanced Semiconductor Engineering, Inc. ("ASE") (TAIEX:2311, NYSE:ASX), the world's largest semiconductor assembly and test service provider, to collaborate on the development and commercialization of Invensas Bond Via Array™ (BVA®) technology. ASE will move to the final stage of qualification of Invensas BVA® vertical interconnect technology for Package-on-Package (PoP) applications and begin engaging customers. With Invensas BVA technology, ASE will be able to meet its customers' desire for low profile and low cost PoP solutions for current and future generations of application processors aimed at smartphones and tablets.

Consumer demand for smaller and more advanced mobile electronics creates ever more challenging requirements for chip packaging technologies. Overall package height and assembly cost must be maintained or reduced while accommodating larger and higher performance application processors. Invensas BVA technology enables device manufacturers to address these competing needs, delivering better performance in smaller packages, all while using existing wire bonding manufacturing infrastructure.

"Tessera is a valued partner for ASE, and we are pleased to expand the technology and business relationship between our two companies," said Tien Wu, Chief Operating Officer of ASE. "The Invensas BVA technology will enable us to deliver advanced packaging solutions that will enable us to continue to satisfy our customers' requirements for integrated, low profile, cost-effective advanced packaging solutions."

Invensas BVA technology provides the industry with unmatched tolerance to process variations, which translates into improved yield and cost efficiencies. Further, this technology can be used to provide a cost effective 3D interconnect solution, for System-in-Package (SiP) and a range of other applications.

"We are excited to enter into this agreement with ASE and look forward to continuing to work closely together to proliferate Invensas BVA and future technologies into the market," said Tom Lacey, CEO, Tessera Technologies, Inc. "This agreement paves the way for both companies to deliver next-generation packaging solutions for a diverse range of end products, including smartphones, tablets, and other mobile electronics."

The companies anticipate that advanced packaging capabilities featuring Invensas BVA technology will be available to ASE customers in the second half of 2016. For more information on Invensas BVA technology and other Invensas solutions, please visit www.invensas.com or www.tessera.com.

About Tessera Technologies, Inc.

Tessera Technologies, Inc., including its Invensas and FotoNation subsidiaries, licenses technologies and intellectual property to customers for use in areas such as mobile computing and communications, memory and data storage, and 3D-IC technologies, among others. Our technologies include semiconductor packaging and interconnect solutions, and products and solutions for mobile and computational imaging, including our LifeFocus™, FaceTools™, FacePower™, FotoSavvy™, DigitalAperture™, face beautification, red-eye removal, High Dynamic Range, autofocus, panorama, and image stabilization intellectual property. For more information call +1.408.321.6000 or visit www.tessera.com or www.invensas.com.

About ASE Group

Advanced Semiconductor Engineering, Inc. (ASE Group) is the world's largest provider of independent semiconductor

manufacturing services in assembly, test, materials and design manufacturing. As a global leader geared toward meeting the industry's ever-growing needs for faster, smaller and higher performance chips, ASE develops and offers a wide portfolio of technology and solutions including IC test program design, front-end engineering test, wafer probe, wafer bump, substrate design and supply, wafer level package, flip chip, System in Package (SiP), final test and electronic manufacturing services. ASE generated sales revenues of US $8.64 billion in 2015 and employs over 65,000 people worldwide. For more information about ASE Group, visit www.aseglobal.com.

Safe Harbor Statement

This press release contains forward-looking statements, which are made pursuant to the safe harbor provisions of the Private Securities Litigation Reform Act of 1995. Forward-looking statements involve risks and uncertainties that could cause actual results to differ significantly from those projected, particularly with respect to the characteristics, benefits, and features of BVA technology and the use of such technologies by ASE. Material factors that may cause results to differ from the statements made include the plans or operations relating to the businesses of Tessera Technologies, Inc. (the "Company"); market or industry conditions; changes in patent laws, regulation or enforcement, or other factors that might affect the Company's ability to protect or realize the value of its intellectual property; the expiration of license agreements and the cessation of related royalty income; the failure, inability or refusal of licensees to pay royalties; initiation, delays, setbacks or losses relating to the Company's intellectual property or intellectual property litigations, or invalidation or limitation of key patents; fluctuations in operating results due to the timing of new license agreements and royalties, or due to legal costs; the risk of a decline in demand for semiconductors and products utilizing FotoNation technologies; failure by the industry to use technologies covered by the Company's patents; the expiration of the Company's patents; the Company's ability to successfully complete and integrate acquisitions of businesses; the risk of loss of, or decreases in production orders from, customers of acquired businesses; financial and regulatory risks associated with the international nature of the Company's businesses; failure of the Company's products to achieve technological feasibility or profitability; failure to successfully commercialize the Company's products; changes in demand for the products of the Company's customers; limited opportunities to license technologies due to high concentration in the markets for semiconductors and related products and smartphone imaging; and the impact of competing technologies on the demand for the Company's technologies. You are cautioned not to place undue reliance on the forward-looking statements, which speak only as of the date of this release. The Company's filings with the Securities and Exchange Commission, including its Annual Report on Form 10-K for the year ended Dec. 31, 2015, include more information about factors that could affect the Company's financial results. The Company assumes no obligation to update information contained in this press release. Although this release may remain available on the Company's website or elsewhere, its continued availability does not indicate that the Company is reaffirming or confirming any of the information contained herein.

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